

Parameter	Rating	Units
Blocking Voltage	600	V <sub>P</sub>
Load Current	120	mA <sub>rms</sub> / mA <sub>DC</sub>
On-Resistance (max)	35	Ω

#### **Features**

- $\bullet$  5000V $_{\rm rms}$  Input/Output Isolation
- 600V<sub>P</sub> Blocking Voltage
- 100% Solid State
- Low Drive Power Requirements (TTL/CMOS Compatible)
- · Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 4-Pin Package
- · Machine Insertable, Wave Solderable

# **Applications**

- Instrumentation
  - Multiplexers
  - Data Acquisition
  - Electronic Switching
  - I/O Subsystems
- · Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

### **Description**

The CPC1394 is a single-pole, normally-open (1-Form-A) Solid State Relay with an enhanced input to output isolation barrier of 5000V<sub>rms</sub>.

The relay output is constructed with efficient MOSFET switches that use IXYS Integrated Circuits Division's patented OptoMOS architecture. The input, a highly efficient GaAlAS infrared LED, controls the optically coupled output.

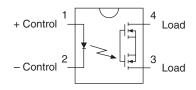
# **Approvals**

- UL Certified Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN/IEC 60950-1 Certified Component: TUV Certificate B 10 05 49410 006

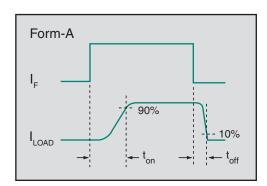
# **Ordering Information**

Part Number	Description
CPC1394G	4-Pin DIP (100/Tube)
CPC1394GV	4-Pin DIP V-Bend (100/Tube)
CPC1394GR	4-Pin Surface Mount (100/Tube)
CPC1394GRTR	4-Pin Surface Mount (1000/Reel)

# **Pin Configuration**



Switching Characteristics of Normally Open Devices











# **Absolute Maximum Ratings @ 25°C**

Parameter	Ratings	Units
Peak Blocking Voltage	600	$V_P$
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	Α
Input Power Dissipation <sup>1</sup>	100	mW
Total Package Dissipation <sup>2</sup>	550	mW
Isolation Voltage, Input to Output	5000	$V_{rms}$
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

<sup>1</sup> Derate linearly 1.33 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

# **Electrical Characteristics @ 25°C**

Parameters	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics						
Load Current						
Continuous	-	Ι <sub>L</sub>	-	-	120	mA <sub>rms</sub> / mA <sub>DC</sub>
Peak	t=10ms	I <sub>LPK</sub>	-	-	±400	mA <sub>P</sub>
On-Resistance <sup>1</sup>	I <sub>L</sub> =120mA	R <sub>ON</sub>	-	26	35	Ω
Off-State Leakage Current	$V_L = 600 V_P$	I <sub>LEAK</sub>	-	-	1	μΑ
Switching Speeds						
Turn-On	$I_F=5mA, V_L=10V$	t <sub>on</sub>	-	0.85	5	
Turn-Off		t <sub>off</sub>	-	0.46	3	ms
Output Capacitance	I <sub>F</sub> =0mA, V <sub>L</sub> =50V, f=1MHz	C <sub>OUT</sub>	-	50	-	pF
Input Characteristics						
Input Control Current to Activate <sup>2</sup>	I <sub>L</sub> =120mA	I <sub>F</sub>	-	0.45	2	А
Input Control Current to Deactivate	-	I <sub>F</sub>	0.2	0.4	-	mA
Input Voltage Drop	I <sub>F</sub> =5mA	$V_{F}$	0.9	1.2	1.4	V
Reverse Input Current	V <sub>R</sub> =5V	I <sub>R</sub>	-	-	10	μΑ
Common Characteristics	Common Characteristics					
Input to Output Capacitance	-	C <sub>I/O</sub>	-	3	-	pF

<sup>&</sup>lt;sup>1</sup> Measurement taken within 1 second of on-time.

<sup>&</sup>lt;sup>2</sup> Derate linearly 3.00 mW / °C

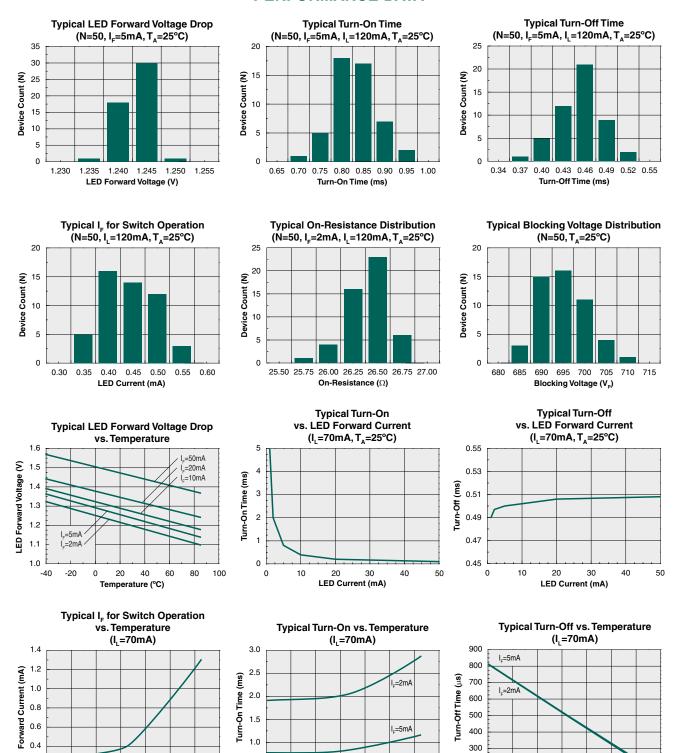
<sup>&</sup>lt;sup>2</sup> For temperatures >60°C, a LED current of 4mA is recommended.



0.2

-40 -20 0 20

#### **PERFORMANCE DATA\***



0.5

100

-40 -20 0 20 40 60

60 80

40

LED Forward Voltage (V)

Temperature (°C)

200

100

80

-40 -20 0

20 40

Temperature (°C)

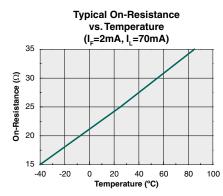
60 80

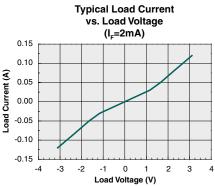
100

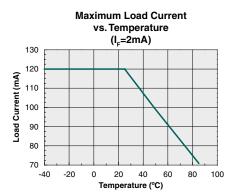
<sup>\*</sup>The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

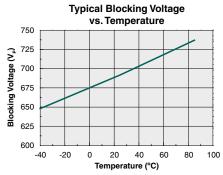


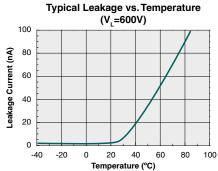
### **PERFORMANCE DATA\***

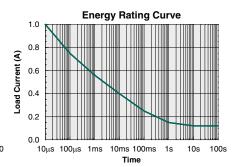












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<sup>\*</sup>The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



# **Manufacturing Information**

### **Moisture Sensitivity**

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC1394G / CPC1394GV / CPC1394GR	MSL 1

#### **ESD Sensitivity**



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

#### **Reflow Profile**

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
CPC1394G / CPC1394GV / CPC1394GR	250°C for 30 seconds

#### **Board Wash**

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.



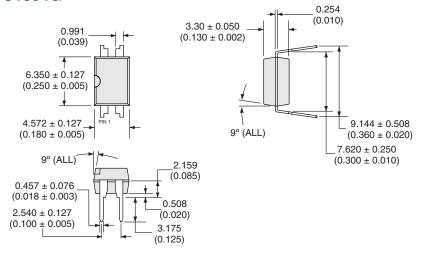




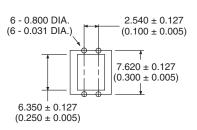


#### **MECHANICAL DIMENSIONS**

### **CPC1394G**

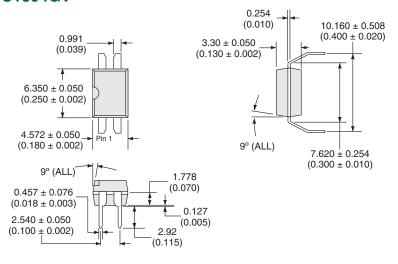


#### PC Board Pattern (Top View)

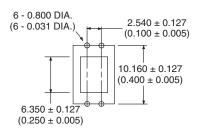


Dimensions mm (inches)

#### **CPC1394GV**



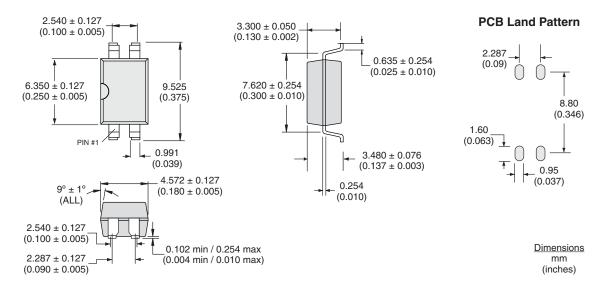
### PC Board Pattern (Top View)



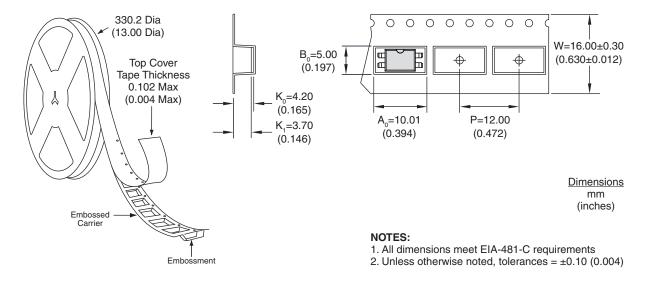
Dimensions mm (inches)



#### **CPC1394GR**



# **CPC1394GRTR Tape & Reel**



#### For additional information please visit our website at: www.ixysic.com

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